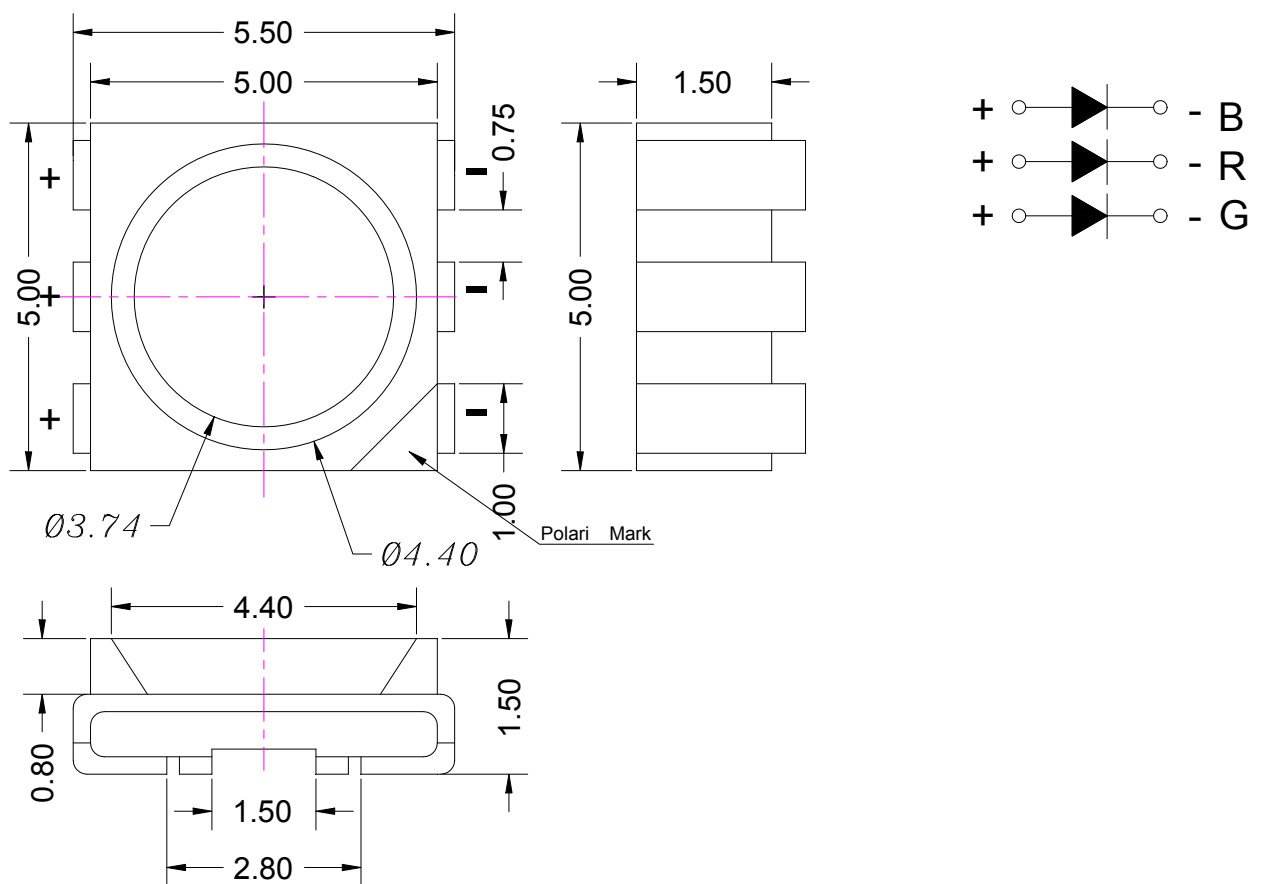




Wen Li	Fang Yang	Jiang Yang	Fang Wang



Tolerance: 0.25(0.01)



Uni mm

Color RGB

Len -color Wa er clear

Emi ing Ma erial InGaN

Dra ing b oli a ion



3 Characteristic

Forward current	If	30	mA			
Reverse voltage	Vr	5	V			
Power dissipation	Pd	110	mW			
Operating temperature range	Top	-25 +80	C			
Storage temperature range	T g	-30 +80	C			
Peak pulsed current 1/8 d f=1KH	lfp	125	mA			
Wavelength at peak emission (R)	If=20mA	peak	620	625	630	nm
Wavelength at peak emission (G)			515	520	525	
Wavelength at peak emission (B)			460	465	470	
Spectral half bandwidth	If=20mA			10		
Forward voltage (R)	If=20mA	Vf	1.8	2.0	2.4	V
Forward voltage (G)			3.0	3.3	3.6	
Forward voltage (B)			3.0	3.3	3.6	
Luminous intensity (R)	If=20mA	I	800	1000	1200	mcd
Luminous intensity (G)			3000	3500	4000	
Luminous intensity (B)			400	500	600	
Viewing angle at 50% IV	If=10mA		--	120	--	Deg
Reverse current	Vr=5V	Ir	--	--	5	A



A

U ef I life	-	IF=20mA	100000			H
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Typical Electrical/Optical Characteristics Curve
(Ta=25 Unless Otherwise Noted)

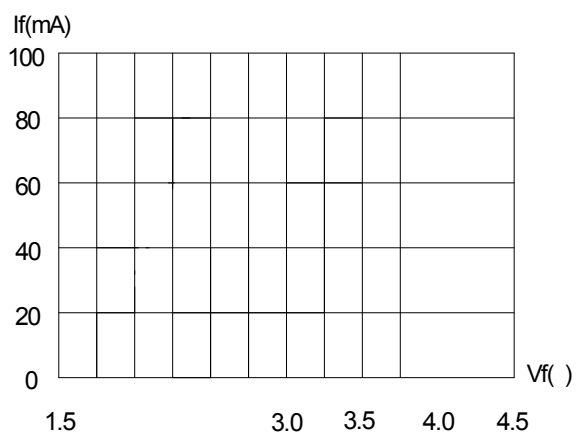


Fig.1 For and C rren For and Vol age)

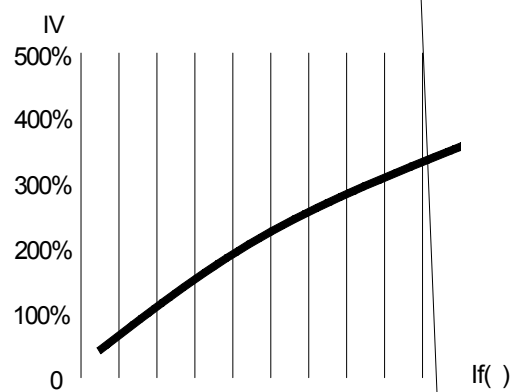


Fig.2 Relazione Lineare Inversa

2

H

ASSOCI

Soldering Technique

i Iron Soldering: The Iron (max 30W) end temperature is less than 300°C, soldering time 3 seconds, soldering position is minimum 2mm from board.

ii Dip Soldering: Max temperature is 260°C, time 5s, the position is minimum 2mm from board.

i Brackets must be bent only if 2mm from colloid.

ii Brackets must be finished by fire or professionally.

iii Brackets must be finished before soldering.

i Brackets must hold at least the connection between the pin, the distance gap of lead and the circuit board.

i. It should be paid attention to the ordering of the device in case of wrong position. The device can be too close to the heat component, causing components to be damaged.

ii. It should not allow the LED heat to lead to deformation.

iii. When deciding the assembly in holes, according to the distance of the lead and the distance of the lead.

iv. Soldering should be done with a good soldering iron.

